

REV: 7-89	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY DOCKET NO. 71-579.2	SERIAL NUMBER 08/12/93 2
37 C.F.R. 1.98(b)	INFORMATION DISCLOSURE STATEMENT BY APPLICANT	APPLICANT Tuttle, et al.	FILING DATE 10/14/93
73 1993	733028285	GROUP 1304	7/16/94

U.S. PATENT DOCUMENTS

EXMNR INITL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	
	AA					
	AB					
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	AE					
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	AG					
	AH					
	AI					
	AJ					

FORIEGN PATENT DOCUMENTS

EXMNR INITL	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATIO N
						YES NO
	AL					
	AM					
	AN					
	AO					

OTHER ART

(include Author, Title, Date, Pertinent Pages, Publisher)

PR	AP		Keith Casson and Kelly Habeck, "High Temperature Packaging: Flip Chip on Flexible Laminate," January 1992, Surface Mount Technology pp 19-20.
PR	AQ		R. Wayne Johnson, "Polymer Thick Films: Technology and Materials," Circuits Manufacturing July 1982.
PR	AR		Ken Gilleo, "Using SM Devices On Flexible Circuitry," March 1986, Electri-onics, pp 20-23.

Examiner <i>Paul Rivard</i>	DATE CONSIDERED 1/6/95
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EXAMINER: Initial if the reference was considered, whether or not the citation is in conformance with MPEP 609. Draw a line through citation if not considered. Include a copy of this form with the next communication to the Applicant.